Packaging Sessions at SEMICON West Expand to Reflect Latest Innovations in Mobile, 3D IC, Cost Reduction, MEMS, LEDs and More

SEMI

The SEMICON West 2012 exhibition at Moscone Center in San Francisco, from July 10-12, will present the most comprehensive program on advanced techniques and solutions for micro and nano-electronics packaging in its 40 year history. Leading device manufacturers, outsource semiconductor packaging and test companies (OSATS), fabless semiconductor companies, top equipment and materials suppliers, academia and research consortiums all will give presentations on the latest trends, technologies and roadmaps for contemporary, advanced and specialized packaging solutions for semiconductors, MEMS, and LEDs. Dedicated programs will be conducted in 2.5/3D packaging, advanced packaging, MEMS packaging, and the packaging roadmap for the International Technology Roadmap for Semiconductors (ITRS).

Packaging Sessions at SEMICON West

At TechXPOT North, Moscone Center, on Tuesday morning, the **Contemporary Packaging: Achieving Cost Advantage through Innovation** [1] **session will** delve into the growing complexity, growth and new cost-down solutions in established technologies, particularly in the analog, power and automotive spaces. The session will focus on the optimization of technologies such as cu wire bond, flip chip, large matrix format and advanced leadframe packages and features speakers from ASM Pacific Technology, Kulicke & Soffa, Texas Instruments and STATSChipPac.

At the San Francisco Marriott Marquis on Tuesday afternoon, the IEEE/CPMT will present a workshop entitled, "THIN IS IN": Thin Chip & Packaging Technologies as Enabler for Innovative Mobile Devices [2]**.** Speakers from Amkor Technology, ASE Group, Flip Chip International, Qualcomm CDMA Technologies, and STATSChipPAC will take on thin 3D-packaging issues and share their perspectives on what's ready for commercialization and future directions and opportunities in this emerging area.

On Wednesday afternoon at TechXPOT North, Moscone Center, the 2.5 & 3D Packaging Landscape for 2015 & Beyond [3] **session examines** how 3D fits into the landscape in 2015 and beyond — revealing what the market and supply chain will need to look like to drive true volume production and adoption of recent advancements in 2.5D (interposer) and 3D packaging. Experts will present from Altera, Fujitsu Integrated Microtechnology, Georgia Institute of Technology, and HiSilicon Technologies, with John Lau, ITRI, and Bill Bottoms, 3MTS, moderating the panel discussion.

With the dramatic explosion of MEMS devices occurring in mobile phones, tablets, gaming consoles, automotive applications, and other areas, the heterogeneous integration of MEMS and ICs has become one of the most innovative areas of packaging innovation in the micro and nano-electronics field. On Thursday morning, at TechXPOT North, Moscone Center, a session entitled MEMS and Sensor Packaging [4] will examine the latest packaging trends, solutions and techniques for a range of MEMS devices, from pressure sensors, RF-MEMS, accelerometers, and gyroscopes to microphones, microactuators, compasses, CMOS image sensors, chemical sensors, microfluidics, mirrors, and displays. LED Packaging will also be addressed in the Wednesday full-day session, Enabling the Next Generation of HB-LEDs [5], at TechXPOT South, Moscone Center.

In addition to the free TechXPOT presentations and workshops, SEMICON West 2012 will also hold SEMI International Standards meetings on 3D Stacked ICs. For more information see www.semi.org/standards [6].

Packaging technology sessions at SEMICON West 2012 are developed and provided by the guidance of the SEMI Advanced Packaging Committee, SEMI Americas, comprised of leading suppliers, device makers, fabless semiconductor firms and packaging outsource companies.

More information on packaging sessions at SEMICON West is available at www.semiconwest.org/Segments/Packaging [7]. For general information (registration, exhibiting, other programs) on SEMICON West, please visit www.semiconwest.org [8].

Premier sponsors of SEMICON West 2012 are Advantest, Applied Materials, and KLA-Tencor.

About SEMI

SEMI is the global industry association serving the nano- and microelectronics manufacturing supply chains. SEMI member companies are the engine of the future, enabling smarter, faster and more economical products that improve our lives. Since 1970, SEMI has been committed to helping members grow more profitably, create new markets and meet common industry challenges. SEMI maintains offices in Beijing, Bengaluru, Berlin, Brussels, Grenoble, Hsinchu, Moscow, San Jose, Seoul, Shanghai, Singapore, Tokyo, and Washington, D.C. For more information, visit www.semi.org.

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Links:
[1] http://www.semiconwest.org/node/8511
[2] http://www.semiconwest.org/node/8661
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